2021 The 6th International Conference on Mechanical and Electronics Engineering is to be held in Osaka, Japan during May 10-12, 2021

ICMEE 2021 is the premier forum for the presentation of new advances and research results in the fields of theoretical, experimental, and applied Mechanical and Electronics Engineering. The conference will bring together leading researchers, engineers and scientists in the domain of interest from around the world.

Accepted papers can be published in ICMEE IOP proceedings, Materials Science and Engineering and indexed by Scopus etc

Important Dates

Paper Submission Deadline: Jan. 05, 2021
Notification of Paper Acceptance: Jan. 25, 2021
Registration Deadline: Feb. 10, 2021

Submission Methods

1. Send your manuscript directly to conference official email: icmee@outlook.com
2. Submit your paper through easychair system: http://confsys.iconf.org/submission/icmee2021

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Scopes

The works that will be presented and published at conference will focus on, but are not limited to, the following topics:

Mechanical Engineering
Aerodynamics Material Engineering
Automation, Mechatronics and Robotics
Mechanical Design
Automobiles Mechanical Power Engineering
Automotive Engineering Mechatronics
Ballistics MEMS and Nano Technology
Biomechanics Multibody Dynamics

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